900603309 03/18/2021

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM632919

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST
SEQUENCE:	1

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
ATOTECH DEUTSCHLAND GMBH		03/18/2021	Gesellschaft Mit Beschränkter Haftung (Gmbh): GERMANY
ATOTECH USA, LLC		03/18/2021	Limited Liability Company: DELAWARE

RECEIVING PARTY DATA

Name:	GOLDMAN SACHS BANK USA, as collateral agent
Street Address:	200 West Street
City:	New York
State/Country:	NEW YORK
Postal Code:	10282
Entity Type:	Chartered Bank: NEW JERSEY

PROPERTY NUMBERS Total: 102

Property Type	Number	Word Mark
Registration Number:	3593608	ACIDCLEAN
Registration Number:	0807896	ACTISALT
Registration Number:	0579602	ALKALUME
Registration Number:	1191002	ALPHA
Registration Number:	1455971	ALSTAN
Registration Number:	2603970	ALUMETCH
Registration Number:	2594032	ALUMSEAL
Registration Number:	1427051	ANOKLEEN
Registration Number:	1635201	ARMOR
Registration Number:	3833259	BIO BOOSTER
Registration Number:	2339271	BONDFILM
Registration Number:	2459150	CERABOND
Registration Number:	2521499	COBALLOY
Registration Number:	3232176	CORRO TRIBLUE
Registration Number:	3197089	CORROSIL
Registration Number:	3617969	CORROTRIBLUE

CH $2565.00 3593608

Property Type	Number	Word Mark
Registration Number:	779284	CUFLEX
Registration Number:	1924374	CU-LINK
Registration Number:	3609295	CUPRABASE
Registration Number:	907002	CUPRACID
Registration Number:	3617971	CUPRAETCH
Registration Number:	3673371	CUPRA PRO
Registration Number:	2364524	CUPRAPULSE
Registration Number:	4796106	CUPRATECH
Registration Number:	789867	DUOZINC
Registration Number:	1595920	DURABOND
Registration Number:	2241064	DYNACHROME
Registration Number:	943893	ECOLOZINC
Registration Number:	745643	ECONO-CHROME
Registration Number:	3086502	ECOTRI
Registration Number:	2742826	EDEN
Registration Number:	6177464	ELECTROPURE
Registration Number:	3786523	ELEVEN 11 END OF LIFE VEHICLE EN
Registration Number:	2438138	EVERPLATE
Registration Number:	870598	FERRODEX
Registration Number:	673349	FUMETROL
Registration Number:	1460498	HEEF
Registration Number:	4796107	INITECH
Registration Number:	2595292	INPULSE
Registration Number:	694410	INTERLOX
Registration Number:	0934772	KLEER AID
Registration Number:	2187120	LUMACHROME
Registration Number:	3596957	MAGNIFY
Registration Number:	0764886	MARK
Registration Number:	4431393	MASTER REMOVER
Registration Number:	1943216	MULTIBOND
Registration Number:	1394540	NEOGANTH
Registration Number:	4309433	NEOLINK
Registration Number:	4796108	NICCOTECH
Registration Number:	2506509	NICHEM
Registration Number:	1382726	NIFLOR
Registration Number:	1343698	NIFLOR
Registration Number:	2650225	NIKOTECT
Registration Number:	1193475	NORTEX

Property Type	Number	Word Mark
Registration Number:	823240	NOVIGANTH
Registration Number:	4224620	PALLABOND
Registration Number:	2128462	PD-TECH
Registration Number:	1394539	PRINTOGANTH
Registration Number:	3990390	PROTECTOSTAN
Registration Number:	1076198	PROTOLUX
Registration Number:	766559	QUATRASID
Registration Number:	4156131	RECOTECT
Registration Number:	946153	REFLECTA
Registration Number:	1988409	REFLECTALLOY
Registration Number:	3593609	RESISTSTRIP
Registration Number:	647290	RODIP
Registration Number:	786989	ROGARD
Registration Number:	758971	ROKLEEN
Registration Number:	834938	ROPLATE
Registration Number:	2410592	SATILUME
Registration Number:	1394538	SECURIGANTH
Registration Number:	1239720	NIC
Registration Number:	666740	SILVERLUME
Registration Number:	2441559	SOLDERBOND
Registration Number:	4082886	SPHEROLYTE
Registration Number:	614153	SRHS
Registration Number:	3529591	STANNOPURE
Registration Number:	1363874	SUPREME
Registration Number:	5174285	TECHDIP
Registration Number:	2572820	TECHSEAL
Registration Number:	4941850	TELOTECH
Registration Number:	1129752	TINPEST GARD
Registration Number:	3468468	TRICHROME
Registration Number:	1088444	TRI-CHROME
Registration Number:	3918383	TRIDUR
Registration Number:	1611809	TRI-MAX
Registration Number:	1651249	TRI-MAX
Registration Number:	1064214	TRU-PLATE
Registration Number:	1839149	UNIBRITE
Registration Number:	328162	UNICHROME
Registration Number:	422307	UNICHROME
Registration Number:	2188776	UNICLEAN

Property Type	Number	Word Mark
Registration Number:	5492902	UNICOAT
Registration Number:	3624341	UNIFIX
Registration Number:	2334982	UNIPLATE
Registration Number:	3024158	UNIPREP
Registration Number:	3025193	UNIPREP
Registration Number:	3037242	HV-R
Registration Number:	3078258	UNISTRIP
Registration Number:	2699176	ZINTEK
Registration Number:	991786	ZODIAC
Registration Number:	2886179	ZYLITE

CORRESPONDENCE DATA

Fax Number: 2138924738

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 424-386-4328
Email: dcip@milbank.com, marnold@milbank.com
Correspondent Name: Monica Arnold, Esq.
Address Line 1: 2029 Century Park East, 33rd Floor
Address Line 2: Milbank, LLP
Address Line 4: Los Angeles, CALIFORNIA 90067

ATTORNEY DOCKET NUMBER:	28804.14400
NAME OF SUBMITTER:	Monica Arnold
SIGNATURE:	/s/ Monica Arnold /s/
DATE SIGNED:	03/18/2021

Total Attachments: 40
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INTELLECTUAL PROPERTY SECURITY AGREEMENT

This **INTELLECTUAL PROPERTY SECURITY AGREEMENT** (as amended, amended and restated, supplemented or otherwise modified from time to time, the "IP Security Agreement") dated March 18, 2021 is among the Persons listed on the signature pages hereof (collectively, the "Grantors") and Goldman Sachs Bank USA, as collateral agent (the "Collateral Agent") for the Secured Parties (as defined in the Credit Agreement referred to below).

WHEREAS, ALPHA 3 B.V., a private company with limited liability (besloten vennootschap met beperkte aansparakelijkheid) incorporated under the laws of the Netherlands (the "Parent Borrower"), ALPHA US BIDCO, INC., a Delaware corporation (the "U.S. Subsidiary Borrower"), ATOTECH B.V., a private company with limited liability (besloten vennootschap met beperkte aansprakelijkheid) incorporated under the laws of the Netherlands (the "Dutch Subsidiary Borrower"), ATOTECH DEUTSCHLAND GMBH, a company organized and existing under the laws of Germany (the "German Subsidiary Borrower"), ATOTECH ASIA PACIFIC LIMITED, a company incorporated under the laws of Hong Kong (the "Hong Kong Borrower", and together with the German Subsidiary Borrower, the U.S. Subsidiary Borrower, the Parent Borrower and the Dutch Subsidiary Borrower, the "Borrowers"), ALPHA 2 B.V., a private company with limited liability (besloten vennootschap met beperkte aansprakelijkheid) incorporated under the laws of the Netherlands ("Holdings") have entered into the Credit Agreement dated as of March 18, 2021 (as amended, amended and restated, supplemented or otherwise modified from time to time, the "Credit Agreement"), with the Lenders, the L/C Issuers and the Administrative Agent and the other parties thereto. Capitalized terms defined in the Credit Agreement or in the Security Agreement (as defined below) and not otherwise defined herein are used herein as defined in the Credit Agreement or the Security Agreement, as the case may be (and in the event of a conflict, the applicable definition shall be the one given to such term in the Security Agreement).

WHEREAS, as a condition precedent to the making of the Loans by the Lenders from time to time and the issuance of Letters of Credit by the L/C Issuers from time to time, the entry into Secured Hedge Agreements by the Hedge Banks from time to time and the entry into Secured Cash Management Agreements by the Cash Management Banks from time to time, each Grantor has executed and delivered that certain Security Agreement dated March 18, 2021 (as amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Security Agreement"), among the Grantors from time to time party thereto and the Collateral Agent.

WHEREAS, under the terms of the Security Agreement, the Grantors have granted to the Collateral Agent, for the benefit of the Secured Parties, a security interest in, among other property, certain intellectual property of the Grantors, and have agreed thereunder to execute this IP Security Agreement for recording with the USPTO and/or the USCO, as applicable.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each Grantor agrees as follows:

Section 1. Grant of Security. Each Grantor hereby collaterally assigns and pledges to the Collateral Agent (and its permitted successors and permitted assigns), for the benefit of the Secured Parties, and each Grantor hereby grants to the Collateral Agent (and its permitted successors and permitted assigns), for the benefit of the Secured Parties, a security interest in all of such Grantor's right, title and interest in and to the following, whether now owned or hereafter acquired by the undersigned (the "Collateral"):

(i) all patents and patent applications, including, without limitation, those set forth in Schedule A hereto (the "Patents");

(ii) all trademark and service mark registrations and applications, including, without limitation, those set forth in Schedule B hereto (provided that no security interest shall be granted in United States intent-to-use trademark applications to the extent that, and so long as creation of a security interest therein or the assignment thereof would result in the loss of any material rights therein), together with the goodwill symbolized thereby (the "Trademarks");

(iii) all copyrights, whether registered or unregistered, including, without limitation, the copyright registrations and applications and exclusive copyright licenses set forth in Schedule C hereto (the "Copyrights");

(iv) all reissues, divisions, continuations, continuations-in-part, extensions, renewals and reexaminations of any of the foregoing, all rights in the foregoing provided by international treaties or conventions, all rights corresponding thereto throughout the world and all other rights of any kind whatsoever of such Grantor accruing thereunder or pertaining thereto;

(v) any and all claims for damages and injunctive relief for past, present and future infringement, dilution, misappropriation, violation, misuse or breach with respect to any of the foregoing, with the right, but not the obligation, to sue for and collect, or otherwise recover, such damages; and

(vi) any and all proceeds of, collateral for, income, royalties and other payments now or hereafter due and payable with respect to, and supporting obligations relating to, any and all of the Collateral of or arising from any of the foregoing;

provided that notwithstanding anything to the contrary contained in the foregoing clauses (i) through (vi), the security interest created hereby shall not extend to, and the term "Collateral" shall not include, any Excluded Assets.

Section 2. Security for Obligations. The grant of a security interest in, the Collateral by each Grantor under this IP Security Agreement secures the payment of all Secured Obligations of such Grantor now or hereafter existing under or in respect of the Secured Documents (as such Secured Documents may be amended, amended and restated, supplemented, replaced, refinanced or otherwise modified from time to time (including any increases of the principal amount outstanding thereunder)), whether direct or indirect, absolute or contingent, and whether for principal, reimbursement obligations, interest, premiums, penalties, fees, indemnifications, contract causes of action, costs, expenses or otherwise. Without limiting the generality of the foregoing, this IP Security Agreement secures, as to each Grantor, the payment of all amounts that constitute part of the Secured Obligations that would be owed by such Grantor to any Secured Party under the Secured Documents but for the fact that they are unenforceable or not allowable due to the existence of a bankruptcy, or reorganization or similar proceeding involving a Loan Party.

Section 3. Recordation. Each Grantor authorizes and requests that the Register of Copyrights, the Commissioner for Patents and the Commissioner for Trademarks record this IP Security Agreement.

Section 4. Execution in Counterparts. This IP Security Agreement may be executed in any number of counterparts, each of which when so executed shall be deemed to be an original and all of which taken together shall constitute one and the same agreement. Delivery of an executed counterpart of a signature page to this IP Security Agreement by telecopier or in .pdf or similar format by electronic mail shall be effective as delivery of an original executed counterpart of this IP Security Agreement.

Section 5. Grants, Rights and Remedies. This IP Security Agreement has been entered into in conjunction with the provisions of the Security Agreement. Each Grantor does hereby acknowledge and confirm that the grant of the security interest hereunder to, and the rights and remedies of, the Collateral Agent with respect to the Collateral are more fully set forth in the Security Agreement, the terms and provisions of which are incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this IP Security Agreement and the terms of the Security Agreement, the terms of the Security Agreement shall govern.

Section 6. Governing Law; Jurisdiction; Etc. (a) THIS IP SECURITY AGREEMENT SHALL BE GOVERNED BY, AND CONSTRUED IN ACCORDANCE WITH, THE LAW OF THE STATE OF NEW YORK WITHOUT GIVING EFFECT TO THE CONFLICTS OF LAWS PRINCIPLES THEREOF, BUT INCLUDING SECTION 5-1401 OF THE NEW YORK GENERAL OBLIGATIONS LAW.

(a) EACH PARTY HERETO IRREVOCABLY AND UNCONDITIONALLY SUBMITS, FOR ITSELF AND ITS PROPERTY, TO THE EXCLUSIVE JURISDICTION OF THE COURTS OF THE STATE OF NEW YORK SITTING IN NEW YORK CITY IN THE BOROUGH OF MANHATTAN AND OF THE UNITED STATES DISTRICT COURT FOR THE SOUTHERN DISTRICT OF NEW YORK SITTING IN THE BOROUGH OF MANHATTAN, AND ANY APPELLATE COURT FROM ANY THEREOF, IN ANY ACTION OR PROCEEDING ARISING OUT OF OR RELATING TO THIS IP SECURITY AGREEMENT, OR FOR RECOGNITION OR ENFORCEMENT OF ANY JUDGMENT, AND EACH OF THE PARTIES HERETO IRREVOCABLY AND UNCONDITIONALLY AGREES THAT ALL CLAIMS IN RESPECT OF ANY SUCH ACTION OR PROCEEDING MAY BE HEARD AND DETERMINED IN SUCH NEW YORK STATE COURT OR, TO THE FULLEST EXTENT PERMITTED BY APPLICABLE LAW, IN SUCH FEDERAL COURT. EACH OF THE PARTIES HERETO AGREES THAT A FINAL JUDGMENT IN ANY SUCH ACTION OR PROCEEDING SHALL BE CONCLUSIVE AND MAY BE ENFORCED IN OTHER JURISDICTIONS BY SUIT ON THE JUDGMENT OR IN ANY OTHER MANNER PROVIDED BY LAW. NOTHING IN THIS IP SECURITY AGREEMENT SHALL AFFECT ANY RIGHT THAT THE ADMINISTRATIVE AGENT, THE COLLATERAL AGENT, ANY LENDER OR ANY L/C ISSUER MAY OTHERWISE HAVE TO BRING ANY ACTION OR PROCEEDING RELATING TO THIS AGREEMENT OR ANY OTHER LOAN DOCUMENT OR THE RECOGNITION OR ENFORCEMENT OF ANY JUDGMENT AGAINST ANY LOAN PARTY OR ITS PROPERTIES IN THE COURTS OF ANY JURISDICTION.

(b) EACH PARTY HERETO IRREVOCABLY AND UNCONDITIONALLY WAIVES, TO THE FULLEST EXTENT PERMITTED BY APPLICABLE LAW, ANY OBJECTION THAT IT MAY NOW OR HEREAFTER HAVE TO THE LAYING OF VENUE OF ANY ACTION OR PROCEEDING ARISING OUT OF OR RELATING TO THIS IP SECURITY AGREEMENT IN ANY COURT REFERRED TO IN PARAGRAPH (b) OF THIS SECTION. EACH OF THE PARTIES HERETO HEREBY IRREVOCABLY WAIVES, TO THE FULLEST EXTENT PERMITTED BY APPLICABLE LAW, THE DEFENSE OF AN INCONVENIENT FORUM TO THE MAINTENANCE OF SUCH ACTION OR PROCEEDING IN ANY SUCH COURT.

(c) EACH PARTY HERETO IRREVOCABLY CONSENTS TO SERVICE OF PROCESS IN THE MANNER PROVIDED FOR NOTICES IN SECTION 10.02 OF THE CREDIT AGREEMENT. NOTHING IN THIS IP SECURITY AGREEMENT WILL AFFECT THE RIGHT OF ANY PARTY HERETO TO SERVE PROCESS IN ANY OTHER MANNER PERMITTED BY APPLICABLE LAW.

(d) EACH PARTY TO THIS IP SECURITY AGREEMENT HEREBY EXPRESSLY WAIVES ANY RIGHT TO TRIAL BY JURY OF ANY CLAIM, DEMAND, ACTION OR CAUSE OF ACTION ARISING UNDER THIS IP SECURITY AGREEMENT OR IN ANY WAY CONNECTED WITH OR RELATED OR INCIDENTAL TO THE DEALINGS OF THE PARTIES HERETO OR ANY OF THEM WITH RESPECT TO THIS IP SECURITY AGREEMENT, OR THE TRANSACTIONS RELATED THERETO, IN EACH CASE WHETHER NOW EXISTING OR HEREAFTER ARISING, AND WHETHER FOUNDED IN CONTRACT OR TORT OR OTHERWISE; AND EACH PARTY HEREBY AGREES AND CONSENTS THAT ANY SUCH CLAIM, DEMAND, ACTION OR CAUSE OF ACTION SHALL BE DECIDED BY COURT TRIAL WITHOUT A JURY, AND THAT ANY PARTY TO THIS IP SECURITY AGREEMENT MAY FILE AN ORIGINAL COUNTERPART OR A COPY OF THIS SECTION 6(e) WITH ANY COURT AS WRITTEN EVIDENCE OF THE CONSENT OF THE SIGNATORIES HERETO TO THE WAIVER OF THEIR RIGHT TO TRIAL BY JURY.

IN WITNESS WHEREOF, each Grantor and the Collateral Agent have caused this IP Security Agreement to be duly executed and delivered by its officer thereunto duly authorized as of the date first written above.

ATOTECH DEUTSCHLAND GMBH

DocuSigned by:
By: Peter Frauenknecht
FED74F66C3294D6...
Name: Peter Frauenknecht
Title: Managing Director

By: ____________________
Name: Tim Hashagen
Title: Authorized Signatory

ATOTECH USA, LLC

By: ____________________
Name: David Balcerzak
Title: Treasurer

IN WITNESS WHEREOF, each Grantor and the Collateral Agent have caused this IP Security Agreement to be duly executed and delivered by its officer thereunto duly authorized as of the date first written above.

ATOTECH DEUTSCHLAND GMBH

By: ___________________________________
Name: Peter Frauenknecht
Title: Managing Director

DocuSigned by:
By: Tim Hashagen
E5907E0AB7D0472...
Name: Tim Hashagen
Title: Authorized Signatory

ATOTECH USA, LLC

By: ___________________________________
Name: David Balcerzak
Title: Treasurer

[Signature Page to Intellectual Property Security Agreement]

IN WITNESS WHEREOF, each Grantor and the Collateral Agent have caused this IP Security Agreement to be duly executed and delivered by its officer thereunto duly authorized as of the date first written above.

ATOTECH DEUTSCHLAND GMBH

By: ___________________________________
Name: Peter Frauenknecht
Title: Managing Director

By: ___________________________________
Name: Tim Hashagen
Title: Authorized Signatory

ATOTECH USA, LLC

DocuSigned by:
By: David Balcerzak
46B61FFF69AD4A3...
Name: David Balcerzak
Title: Treasurer

GOLDMAN SACHS BANK USA,
as Collateral Agent

By: ______________________________
Name: Thomas Manning
Title: Authorised Signatory

[Signature Page to Intellectual Property Security Agreement]

<u>Patents, Trademarks and Copyrights</u>

Patents

Issued Patents:

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	CONTACT ELEMENT	6887113	03-May-2005
ATOTECH DEUTSCHLAND GMBH	Aqueous, alkaline, cyanide-free zinc (alloy) plating bath containscationic polycondensate of N,N'-bis(dialkylaminoalkyl)urea anddihaloalkane.	6652728	25-Nov-2003
ATOTECH DEUTSCHLAND GMBH	FILM-STRIPPING PROCESS	6059919	09-May-2000
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR THE ELECTROLYTIC DEPOSITION OF METAL LAYERS	6099711	08-Aug-2000
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR MAINTAINING A CONSTANT CONCENTRATION OF SUBSTANCES IN AN ELECTROPLATING BATH	6083374	04-Jul-2000
ATOTECH DEUTSCHLAND GMBH	PROCESS AND SYSTEM FOR ELECTROCHEMICAL TREATMENT OF LONG STRETCHED-OUT ITEMS	6168691	02-Jan-2001
ATOTECH DEUTSCHLAND GMBH	Aqueous bath for electrolytic copper plating.	6425996	30-Jul-2002
ATOTECH DEUTSCHLAND GMBH	PROCESS AND SOLUTION FOR THE PRELIMINARY TREATMENT OF COPPER SURFACES	6562149	13-May-2003
ATOTECH DEUTSCHLAND GMBH	Device for partial electrochemical treatment of bar-shaped objects.	6508926	21-Jan-2003
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR THE ELECTROLYTIC DEPOSITION OF COPPER LAYERS	6129830	10-Oct-2000
ATOTECH DEUTSCHLAND GMBH	Process for the preliminary treatment of copper surfaces.	6723385	20-Apr-2004

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	METHOD FOR APPLYING A METAL LAYER TO A LIGHT METAL SURFACE	7138043	21-Nov-2006
ATOTECH DEUTSCHLAND GMBH	Elektrisches Kontaktierelement aus elastischem Werkstoff.Electrical contact element made of an elastic material.	6926813	09-Aug-2005
ATOTECH DEUTSCHLAND GMBH	Rotary Element for making electrical contact	7033468	25-Apr-2006
ATOTECH DEUTSCHLAND GMBH	Acid galvanic nickel bath	6919014	19-Jul-2005
ATOTECH DEUTSCHLAND GMBH	Acidic Treatment Liquid and Method of treating Copper Surfaces.	7153449	26-Dec-2006
ATOTECH DEUTSCHLAND GMBH	COPPER BATH AND METHOD OF DEPOSITING A MATT COPPER COATING	7074315	11-Jul-2006
ATOTECH DEUTSCHLAND GMBH	METHOD FOR ELECTROLESS NICKEL PLATING	6902765	07-Jun-2005
ATOTECH DEUTSCHLAND GMBH	VERTICAL SYSTEM FOR THE PLATING TREATMENT OF A WORK PIECE AND METHOD FOR CONVEYING THE WORK PIECE	8540853	24-Sep-2013
ATOTECH DEUTSCHLAND GMBH	APPARATUS AND METHOD FOR THE WET CHEMICAL TREATMENT OF A PRODUCT AND METHOD FOR INSTALLING A FLOW MEMBER INTO THE APPARATUS (Lamellenanströmer)	8277602	02-Oct-2012
ATOTECH DEUTSCHLAND GMBH	Segmented counter electrode for an electrolytic treatment system	7473344	06-Jan-2009

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	Method and Conveyorized System for Electrolytically Processing Work Pieces	7563352	21-Jul-2009
ATOTECH DEUTSCHLAND GMBH	Aqueous Alkaline Zincate Solution and Methods	6790265	14-Sep-2004
ATOTECH DEUTSCHLAND GMBH	AQUEOUS ACIDIC IMMERSION PLATING SOLUTIONS AND METHODS FOR PLATING ALUMINUM AND ALLOYS	7407689	05-Aug-2008
ATOTECH DEUTSCHLAND GMBH	COMPOSITION AND PROCESS FOR IMPROVING THE ADHESION OF A SICCATIVE ORGANIC COATING COMPOSITIONS TO METAL SURFACES.	7223299	29-May-2007
ATOTECH DEUTSCHLAND GMBH	BATHS, SYSTEMS AND PROCESSES FOR ELECTROPLATING ZINC-NICKEL TERNARY AND HIGHER ALLOYS AND ARTICLES SO ELECTROPLATED	7442286	28-Oct-2008
ATOTECH DEUTSCHLAND GMBH	Iron-phosphorus electroplating bath and method.	7494578	24-Feb-2009
ATOTECH DEUTSCHLAND GMBH	Chromate-plating bath and process for finishing zinc zinc alloy orcadmium surfaces	5876517	02-Mar-1999
ATOTECH DEUTSCHLAND GMBH	Aqueous composition for desmutting aluminum comprises acid, oxidizingagent and optionally a halogenated compound.	6407047	18-Jun-2002
ATOTECH DEUTSCHLAND GMBH	Aqueous immersion plating bath and method for plating	6063172	16-May-2000
ATOTECH DEUTSCHLAND GMBH	Copper etching compositions and method for etching copper	6086779	11-Jul-2000
ATOTECH DEUTSCHLAND GMBH	Process for whisker-free aqueous electroless tin plating	6361823	26-Mar-2002
ATOTECH DEUTSCHLAND GMBH	Improved adhesion of polymeric materials to metal surfaces (Durabond + BondFilm)	6506314	14-Jan-2003

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	Aqueous plating bath for electrodeposition of tin-zinc alloy, comprisesbath-soluble stannous salt(s), zinc salt(s) and quaternary ammoniumpolymer e.g. ureylene quaternary ammonium polymer.	6436269	20-Aug-2002
ATOTECH DEUTSCHLAND GMBH	CONVEYORIZED PLATING LINE AND METHOD FOR ELECTROLYTICALLY METAL PLATING A WORKPIECE	7449089	11-Nov-2008
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR THE REGULATION OF THE CONCENTRATION OF METAL IONS IN AN ELECTROLYTE AND USE THEREOF	6899803	31-May-2005
ATOTECH DEUTSCHLAND GMBH	Aqueous passivating coating composition for zinc or zinc alloys and method for using same	8262811	11-Sep-2012
ATOTECH DEUTSCHLAND GMBH	DEVICE FOR ELECTROLYTIC TREATMENT OF PRINTED CIRCUIT BOARDS AND CONDUCTIVE FILMS	6238529	29-May-2001
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR REGULATING THE CONCENTRATION OF SUBSTANCES IN ELECTROLYTES	6350362	26-Feb-2002
ATOTECH DEUTSCHLAND GMBH	DEVICE AND METHOD FOR CHEMICALLY AND ELECTROLYTICALLY TREATING WORK PIECES	8656858	25-Feb-2014
ATOTECH DEUTSCHLAND GMBH	DEVICE AND METHOD FOR ELECTROLYTICALLY TREATING FLAT WORK PIECES	7955487	07-Jun-2011
ATOTECH DEUTSCHLAND GMBH	DIRECT ELECTROLYTIC METALLIZATION OF NON-	7025867	11-Apr-2006

Owner	Title	Patent No.	Issue Date
	CONDUCTING SUBSTRATES		
ATOTECH DEUTSCHLAND GMBH	Polyvinylammonium halides and its use in galvanic copper deposition baths	8114263	14-Feb-2012
ATOTECH DEUTSCHLAND GMBH	Anti-corrosion treatment for conversion coatings	8435360	07-May-2013
ATOTECH DEUTSCHLAND GMBH	Solderability Enhancer	8337606	25-Dec-2012
ATOTECH DEUTSCHLAND GMBH	Non etching adhesion promoters	8,945,298	03-Feb-2015
ATOTECH DEUTSCHLAND GMBH	Amino acids and Peptides for use as Levellers in Copper Plating	8679316	25-Mar-2014
ATOTECH DEUTSCHLAND GMBH	Aqueous Alkaline Zincate Solution and Methods	6811819	02-Nov-2004
ATOTECH DEUTSCHLAND GMBH	COMPOSITION AND METHOD FOR IMPROVED ADHESION OF POLYMERIC MATERIALS TO COPPER OR COPPER ALLOY SURFACES	8192636	05-Jun-2012
ATOTECH DEUTSCHLAND GMBH	Means for manufacturing corrosion protection coats on metal surfaces	8,764,916	01-Jul-2014
ATOTECH DEUTSCHLAND GMBH	APPARATUS AND METHOD FOR THE ELECTROLYTIC TREATMENT OF A PLATE-SHAPED PRODUCT (Plater-Single Board Production)	8545687	01-Oct-2013
ATOTECH DEUTSCHLAND GMBH	ELECTROLESS NICKERL PLATING SOLUTIONS	6800121	05-Oct-2004
ATOTECH DEUTSCHLAND GMBH	Zincate pretreatment of magnesium	8231743	31-Jul-2012
ATOTECH DEUTSCHLAND GMBH	Iron-phosphorus electroplating bath and method.	7,588,675	15-Sep-2009
ATOTECH DEUTSCHLAND GMBH	Method for Regeneration of etch cleaners containing ferric salts	7520973	21-Apr-2009
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR THE TRANSFER OF POWDERS	7615256	10-Nov-2009

Owner	Title	Patent No.	Issue Date
	AND POWDER COATINGS TO SUBSTRATES		
ATOTECH DEUTSCHLAND GMBH	Method for depositing copper in apertures with high aspect ratios	8784634	22-Jul-2014
ATOTECH DEUTSCHLAND GMBH	Crystalline Chromium from trivalent Cr salts at high pH	8187448	29-May-2012
ATOTECH DEUTSCHLAND GMBH	Device for electric supply unit in an apparatus for electrochemical treatment	7815777	19-Oct-2010
ATOTECH DEUTSCHLAND GMBH	Control of the desmear and roughening process in the production of printed circuit boards (especially for sequential build up (SBU) or semi additive process (SAP) - technology) by means of gloss measurement.	8137575	20-Mar-2012
ATOTECH DEUTSCHLAND GMBH	Agent for sealing metallic ground coats, especially ground coats consisting of zinc or zinc alloys	6478886	12-Nov-2002
ATOTECH DEUTSCHLAND GMBH	Device and method for electrolytically treating a workpiece at least superficially electrical conducting	7767065	03-Aug-2010
ATOTECH DEUTSCHLAND GMBH	METHOD FOR CONTINUOUSLY OPERATING ACID OR ALKALINE ZINC OR ZINC ALLOY BATHS	8475874	02-Jul-2013
ATOTECH DEUTSCHLAND GMBH	Crystalline chromium deposit from high pH trivalent chromium plating baths	7887930	15-Feb-2011
ATOTECH DEUTSCHLAND GMBH	NITRIC ACID AND CHROMIC ACID-FREE COMPOSITONS AND PROCESS FOR CLEANING ALUMINUM AND ALUMINUM ALLOYS (Orig.)NITRIC ACID AND CHROMIC ACID-FREE COMPOSITONS AND	7384901	10-Jun-2008

Owner	Title	Patent No.	Issue Date
	PROCESS FOR CLEANING ALUMINUM AND ALUMINUM ALLOYS.		
ATOTECH DEUTSCHLAND GMBH	Metal plating composition and method for the deposition of Copper-Zinc-Tin suitable for manufacturing thin film solar cell	9263609	16-Feb-2016
ATOTECH DEUTSCHLAND GMBH	Online Control of galvanic bath additives	9057145	16-Jun-2015
ATOTECH DEUTSCHLAND GMBH	ACIDIC BATH FOR ELECTROLYTICALLY DEPOSITING A COPPER DEPOSIT CONTAINING HALOGENATED OR PSEUDOHALOGENATED MONOMERIC PHENAZINIUM COMPOUNDS	7786303	31-Aug-2010
ATOTECH DEUTSCHLAND GMBH	TREATMENT UNIT FOR THE WET-CHEMICAL OR ELECTROLYTIC TREATMENT OF FLAT WORKPIECES	7993486	09-Aug-2011
ATOTECH DEUTSCHLAND GMBH	METHOD OF MANUFACTURING A CIRCUIT CARRIER AND THE USE OF THE METHOD	8927899	06-Jan-2015
ATOTECH DEUTSCHLAND GMBH	Alkaline galvanizing bath comprising a filtration membrane	8293092	23-Oct-2012
ATOTECH DEUTSCHLAND GMBH	METHOD, CLIP AND DEVICE FOR TRANSPORTING AN ARTICLE TO BE TREATED IN AN ELECTROLYTIC SYSTEM (Folienklammer)	8567590	29-Oct-2013
ATOTECH DEUTSCHLAND GMBH	Electrodialytic regeneration of electroless hypophosphites involves simultaneously guiding bath liquid through dilute compartments in a	6379517	30-Apr-2002

Owner	Title	Patent No.	Issue Date
	cathode and anode having second electrodialysis device		
ATOTECH DEUTSCHLAND GMBH	Nozzle Arrangement	7650897	26-Jan-2010
ATOTECH DEUTSCHLAND GMBH	Mixture of oligomeric phenazinium compounds	7872130	18-Jan-2011
ATOTECH DEUTSCHLAND GMBH	Chrome(VI)-free black passivates for surfaces containing zinc	8460534	11-Jun-2013
ATOTECH DEUTSCHLAND GMBH	MICROBIAL DEGRADATION OF WATER-BORNE PAINT CONTAINING HIGH LEVELS OF ORGANIC SOLVENT	8202424	19-Jun-2012
ATOTECH DEUTSCHLAND GMBH	Antifriction coatings, methods of producing such coatings and articles inlcuding such coatings.	7842403	30-Nov-2010
ATOTECH DEUTSCHLAND GMBH	METHOD OF MANUFACTURING PATTERN-FORMING METAL STRUCTURES ON A CARRIER SUBSTRATE	8202567	19-Jun-2012
ATOTECH DEUTSCHLAND GMBH	Vorbehandlungsverfahren zur direkten leitfähigen Metallisierung von Nichtleitern unter Verwendung eines neuen Culinks	8152914	10-Apr-2012
ATOTECH DEUTSCHLAND GMBH	METHODS OF TREATING A SURFACE TO PROMOTE METAL PLATING AND DEVICES FORMED	8323769	04-Dec-2012
ATOTECH DEUTSCHLAND GMBH	Sulfonated fatty acid additive for electroless nickel plating	8557100	15-Oct-2013
ATOTECH DEUTSCHLAND GMBH	METHOD AND SYSTEM FOR THE TREATMENT OF FLAT FEEDSTOCK, AND DEVICE FüR REMOVING OR KEEPING AWAY TREATMENT LIQUID (Flüssigkeitsentfernung)	9016230	28-Apr-2015

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	SILICON SOLAR CELL	8,759,120	24-Jun-2014
ATOTECH DEUTSCHLAND GMBH	Measurement of Satilume Effect	8405833	26-Mar-2013
ATOTECH DEUTSCHLAND GMBH	Corrosion protection treatment for surfaces made of zinc and zinc coatings	8951363	10-Feb-2015
ATOTECH DEUTSCHLAND GMBH	Acidic plating bath and process for electrolytic deposition and process for deposition of satin bright nickel layers	7361262	22-Apr-2008
ATOTECH DEUTSCHLAND GMBH	Device and method for regenerating an electroless nickel plating bath	7,662,266	16-Feb-2010
ATOTECH DEUTSCHLAND GMBH	Polymers with amino end groups and their use as additives for galvanic zinc and zinc alloy baths	9322107	26-Apr-2016
ATOTECH DEUTSCHLAND GMBH	Treatment solution for producing chromium- and cobalt-free black conversion layers	9005373	14-Apr-2015
ATOTECH DEUTSCHLAND GMBH	White Bronze Plating Bath containing N-methylpyrrolidone	8647491	11-Feb-2014
ATOTECH DEUTSCHLAND GMBH	Highly corrosion resistant NiAu coatings	8304658	06-Nov-2012
ATOTECH DEUTSCHLAND GMBH	Use of thiourea-derivatives for deposition of homogeneous CISe layers	8,828,278	09-Sep-2014
ATOTECH DEUTSCHLAND GMBH	Powder Dispenser for RCF Foil Manufacture	8,715,780	06-May-2014
ATOTECH DEUTSCHLAND GMBH	Composition and method for micro etching of copper and copper alloys	8,758,634	24-Jun-2014
ATOTECH DEUTSCHLAND GMBH	Stress-reduced Ni-Pd Stacks for Bondable or Solderable Waver Surfaces	8986789	24-Mar-2015
ATOTECH DEUTSCHLAND GMBH	Method for Improving the Adhesion Between Silver Surfaces and Resin Materials	8819930	02-Sep-2014

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	Method to form solder alloy deposits on substrates	8497200	30-Jul-2013
ATOTECH DEUTSCHLAND GMBH	Method to form solder deposits on substrates	8507376	13-Aug-2013
ATOTECH DEUTSCHLAND GMBH	A METHOD OF INSPECTING A METAL COATING AND A METHOD FOR ANALYTICAL CONTROL OF A DEPOSITION ELECTROLYTE SERVING TO DEPOSIT SAID METAL COATING	8,894,835	25-Nov-2014
ATOTECH DEUTSCHLAND GMBH	METHOD TO FORM SOLDER DEPOSITS ON SUBSTRATES	8,871,631	28-Oct-2014
ATOTECH DEUTSCHLAND GMBH	Method for control of stabilizer additives in electroless metal and metal alloy plating electrolytes	8648601	11-Feb-2014
ATOTECH DEUTSCHLAND GMBH	Solution and process for increasing the solderability and corrosion resistance of metal or metal alloy surface	8491713	23-Jul-2013
ATOTECH DEUTSCHLAND GMBH	Immersion Tin Plating Bath	9,057,141	16-Jun-2015
ATOTECH DEUTSCHLAND GMBH	Autocatalytic plating bath composition for deposition of tin and tin alloys	8,801,844	12-Aug-2014
ATOTECH DEUTSCHLAND GMBH	Direct Pure Pd surface finish designed for copper wire bonding on printed circuit boards and IC-substrates	8987910	24-Mar-2015
ATOTECH DEUTSCHLAND GMBH	Differential tin etch	9332652	03-May-2016
ATOTECH DEUTSCHLAND GMBH	Wire bondable surface for microelectronic devices	9076773	07-Jul-2015
ATOTECH DEUTSCHLAND GMBH	Electroless Palladium Plating Bath Composition	8,888,903	18-Nov-2014
ATOTECH DEUTSCHLAND GMBH	Method for electroless nickel-phosphorous alloy deposition onto flexible substrates	9089062	21-Jul-2015

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	Process for metallizing nonconductive plastic surfaces (Rack protection)	9181622	10-Nov-2015
ATOTECH DEUTSCHLAND GMBH	Process for metallizing nonconductive plastic surfaces	9051643	09-Jun-2015
ATOTECH DEUTSCHLAND GMBH	Alkaline plating bath for electroless deposition of cobalt alloys (Bleifreies außenstromloses Cobaltwolframbad)	8,961,670	24-Feb-2015
ATOTECH DEUTSCHLAND GMBH	Method and regeneration apparatus for regenerating a plating composition which is suitable for depositing at least one first metal on a substrate	9249510	02-Feb-2016
ATOTECH DEUTSCHLAND GMBH	Plating bath for electroless deposition of nickel layers	9175399	03-Nov-2015
ATOTECH DEUTSCHLAND GMBH	Holding Device for a Product and Treatment Method (Waferhalter)	9222192	29-Dec-2015
ATOTECH DEUTSCHLAND GMBH	Manufacture of coated copper pillars	9331040	03-May-2016
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR IMPROVING THE CORROSION RESISTANCE OF METAL SURFACES AND METAL PIECES HAVING IMPROVED CORRSION RESISTANCE	7,101,469	05-Sep-2006
ATOTECH DEUTSCHLAND GMBH	High current density semi-bright and bright zinc sulfur-acid salt electrogalvanizing process and composition	5788822	04-Aug-1998
ATOTECH DEUTSCHLAND GMBH	Apparatus and method for recovering photoresist developers and strippers	5753135	19-May-1998
ATOTECH DEUTSCHLAND GMBH	Silane compositions	6215011	10-Apr-2001
ATOTECH DEUTSCHLAND GMBH	X-Plating (Redox)	9526183	20-Dec-2016
ATOTECH DEUTSCHLAND GMBH	Method and regeneration apparatus for regenerating a plating composition which is	9435041	06-Sep-2016

Owner	Title	Patent No.	Issue Date
	suitable for depositing at least one first metal on a substrate		
ATOTECH DEUTSCHLAND GMBH	METHOD FOR CATHODIC CORROSION PROTECTION OF CHROMIUM SURFACES	9441306	September 13, 2016
ATOTECH DEUTSCHLAND GMBH	METHOD FOR ACTIVATING A COPPER SURFACE FOR ELECTROLESS PLATING	9441299	September 13, 2016
ATOTECH DEUTSCHLAND GMBH	Device for vertical galvanic metal, preferably copper, deposition on a substrate and a container suitable for receiving such a device (Baukasten)	9534310	January 3, 2017
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR CORROSION PROTECTION OF IRON CONTAINING MATERIALS	9435047	September 6, 2016
ATOTECH DEUTSCHLAND GMBH	AQUEOUS COMPOSITION FOR ETCHING OF COPPER AND COPPER ALLOYS	9441304	September 13, 2016
ATOTECH DEUTSCHLAND GMBH	METHOD FOR MANUFACTURE OF WIRE BONDABLE AND SOLDERABLE SURFACES ON NOBLE METAL ELECTRODES	9401466	July 26, 2016
ATOTECH DEUTCHLAND GMBH	DEVICE AND METHOD FOR THE TREATMENT OF FLAT MATERIAL TO BE TREATED (Niveauregulierung)	9394622	July 19, 2016
ATOTECH DEUTCHLAND GMBH	Electroless Nickel Plating Bath (Low temperature NiP)	9399820	July 26, 2016
ATOTECH DEUTSCHLAND GMBH	METHOD FOR COPPER PLATING	9506158	November 29, 2016
ATOTECH DEUTSCHLAND GMBH	SOLUTION AND PROCESS FOR THE PRE-TREATMENT OF COPPER SURFACES USING AN N-ALKOXYLATED ADHESION-PROMOTING COMPOUND	9504161	November 22, 2016

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	METHOD FOR ELECTROLESS PLATING OF TIN AND TIN ALLOYS	9458541	October 4, 2016
ATOTECH DEUTSCHLAND GMBH	X-PLATING	9445510	September 13, 2016
ATOTECH DEUTSCHLAND GMBH	METHOD, TREATMENT STATION, AND SYSTEM FOR THE TREATMENT OF FLAT FEEDSTOCK	9713265	18-Jul-2017
ATOTECH DEUTSCHLAND GMBH	Process for forming corrosion protection layers on metal surfaces	9738790	22-Aug-2017
ATOTECH DEUTSCHLAND GMBH	ELECTROPLATING BATH AND METHOD FOR PRODUCING DARK CHROMIUM LAYERS	9689081	27-Jun-2017
ATOTECH DEUTSCHLAND GMBH	Method for electroless plating / Metallization of sputtered seed layers	9822034	21-Nov-2017
ATOTECH DEUTSCHLAND GMBH	Method of treating metal surfaces and devices formed thereby	9,763,336	12-Sep-2017
ATOTECH DEUTSCHLAND GMBH	Novel adhesion promoting agents for metallization of substrate surfaces	9920432	20-Mar-2018
ATOTECH DEUTSCHLAND GMBH	Method for manufacture of fine line circuitry	9,713,266	18-Jul-2017
ATOTECH DEUTSCHLAND GMBH	METHOD AND APPARATUS FOR ELECTROLYTICALLY DEPOSITING A DEPOSITION METAL ON A WORKPIECE	9745665	29-Aug-2017
ATOTECH DEUTSCHLAND GMBH	GALVANIC NICKEL OR NICKEL ALLOY ELECTROPLATING BATH FOR DEPOSITING A SEMI-BRIGHT NICKEL OR NICKEL ALLOY	9752244	5-Sep-2017
ATOTECH DEUTSCHLAND GMBH	Device for vertical galvanic metal deposition on a substrate (Düsenscheibe)	9,631,294	25-Apr-2017

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	Copper plating bath composition	9551080	24-Jan-2017
ATOTECH DEUTSCHLAND GMBH	Plated electrical contacts for solar modules	9680042	13-Jun-2017
ATOTECH DEUTSCHLAND GMBH	Electroless copper plating solution	9650718	16-May-2017
ATOTECH DEUTSCHLAND GMBH	ELECTROPLATING BATH AND METHOD FOR PRODUCING DARK CHROMIUM LAYERS	10,174,432	08-Jan-2019
ATOTECH DEUTSCHLAND GMBH	Method for depositing a copper seed layer onto a barrier layer	10,077,498	18-Sep-2018
ATOTECH DEUTSCHLAND GMBH	Novel adhesion promoting process for metallisation of substrate surfaces	10,487,404	26-Nov-2019
ATOTECH DEUTSCHLAND GMBH	COPPER ELECTROPLATING METHOD	9,963,797	08-May-2018
ATOTECH DEUTSCHLAND GMBH	Composition and process for metallizing nonconductive plastic surfaces	10,174,250	08-Jan-2019
ATOTECH DEUTSCHLAND GMBH	Plating bath composition and method for electroless plating of palladium	9,758,874	12-Sep-2017
ATOTECH DEUTSCHLAND GMBH	PRE-TREATMENT PROCESS FOR ELECTROLESS PLATING	9896765	20-Feb-2018
ATOTECH DEUTSCHLAND GMBH	Method of treating metal surfaces and devices formed thereby	10375835	06-Aug-2019
ATOTECH DEUTSCHLAND GMBH	METHOD OF FORMING A METAL LAYER AND METHOD OF MANUFACTURING A SUBSTRATE HAVING SUCH METAL LAYER	9988730	5-Jun-2018
ATOTECH DEUTSCHLAND GMBH	Advanced Adhesion Promoter Process (BondFilm)	10219391	26-Feb-2019
ATOTECH DEUTSCHLAND GMBH	GALVANIC NICKEL OR NICKEL ALLOY ELECTROPLATING BATH	9790607	17-Oct-2017

Owner	Title	Patent No.	Issue Date
	FOR DEPOSITING A SEMI-BRIGHT NICKEL OR NICKEL ALLOY		
ATOTECH DEUTSCHLAND GMBH	Iron Boron Alloy Coatings and a Process for their Preparation	9783891	10-Oct-2017
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR COATING A SURFACE OF A SUBSTRATE MADE OF NONMETALLIC MATERIAL WITH A METAL LAYER	8962086	24-Feb-2015
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR COATING A SURFACE OF A SUBSTRATE MADE OF NONMETALLIC MATERIAL WITH A METAL LAYER	9249512	02-Feb-2016
ATOTECH DEUTSCHLAND GMBH	Method for reducing the optical reflectivity of a copper and copper alloy circuitry	10,448,515	15-Oct-2019
ATOTECH DEUTSCHLAND GMBH	Acidic zinc and zinc nickel alloy plating bath composition and electroplating method	10,858,747	08-Dec-2020
ATOTECH DEUTSCHLAND GMBH	Method and apparatus for electroplating a metal onto a substrate	10501860	10-Dec-2019
ATOTECH DEUTSCHLAND GMBH	Plating bath composition and method for electroless plating of palladium	10385458	20-Aug-2019
ATOTECH DEUTSCHLAND GMBH	WHITE BRONZE PLATING BATH USING NOVEL ADDITIVES FORMED UPON REACTION OF SECONDARY AMINES AND DIGLYCIDYL ETHERS	9399824	July 26, 2016
ATOTECH DEUTSCHLAND GMBH	METHOD, RETAINING MEANS, APPARATUS AND SYSTEM FOR TRANSPORTING A FLAT MATERIAL FEEDSTOCK, AND LOADING OR UNLOADING DEVICE	9380708	June 28, 2016

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR THE ELECTROLYTIC TREATMENT OF ELECTRICALLY CONDUCTING STRUCTURES WHICH ARE INSULATED FROM EACH OTHER AND POSITIONED ON THE SURFACE OF ELECTRICALLY INSULATING FILM MATERIALS AND USE OF THE METHOD	6979391	December 27, 2005
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR THE ELECTROLYTIC TREATMENT OF ELECTRICALLY CONDUCTING SURFACES SEPARATED PLATES AND FILM MATERIAL PIECES IN ADDITION TO USES OF SAID METHOD	6939455	September 6, 2005
ATOTECH DEUTSCHLAND GMBH	TREATMENT OF CIRCUIT SUPPORT WITH IMPULSE EXCITATION	6908515	June 21, 2005
ATOTECH DEUTSCHLAND GMBH	METHOD OF FORMING A CONDUCTIVE PATTERN ON DIELECTRIC SUBSTRATES	6806034	October 19, 2004
ATOTECH DEUTSCHLAND GMBH	METHOD FOR GALVANICALLY FORMING CONDUCTOR STRUCTURES OF HIGH-PURITY COPPER IN THE PRODUCTION OF INTEGRATED CIRCUITS	6793795	September 21, 2004
ATOTECH DEUTSCHLAND GMBH	METHOD FOR PRODUCING MICROCOMPONENTS	6736983	May 18, 2004
ATOTECH DEUTSCHLAND GMBH	Tin whisker-free printed circuit board	6720499	April 13, 2004
ATOTECH DEUTSCHLAND GMBH	METHOD FOR PRODUCING METALLIZED SUBSTRATE MATERIALS	6706201	March 16, 2004

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	METHOD FOR PRODUCING SOLDERABLE AND FUNCTIONAL SURFACES ON CIRCUIT CARRIERS	6698648	March 2, 2004
ATOTECH DEUTSCHLAND GMBH	CARRIER SERVING TO SUPPLY CURRENT TO WORKPIECES OR COUNTER-ELECTRODES THAT ARE TO BE TREATED ELECTROLYTICALLY AND A METHOD FOR ELECTROLYTICALLY TREATING WORKPIECE	6695961	February 24, 2004
ATOTECH DEUTSCHLAND GMBH	METALLIZATION OF NON-CONDUCTIVE SURFACES WITH SILVER CATALYST AND ELECTROLESS METAL COMPOSITIONS	6645557	November 11, 2003
ATOTECH DEUTSCHLAND GMBH	Method of producing copper surfaces for improved bonding, compositions used therein and articles made therefrom	6602440	August 5, 2003
ATOTECH DEUTSCHLAND GMBH	METHOD FOR FORMING A METAL PATTERN ON A DIELECTRIC SUBSTRATE	6593249	July 15, 2003
Atotech USA, LLC (f/k/a Atotech USA, Inc.)	High current density zinc sulfate electrogalvanizing process and composition	6585812	July 1, 2003
ATOTECH DEUTSCHLAND GMBH	Method of producing copper surfaces for improved bonding, compositions used therein and articles made therefrom	6579591	June 17, 2003
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR THE APPLICATION OF A METAL FILM ON A POLYMER SURFACE OF A SUBJECT	6506293	January 14, 2003
ATOTECH DEUTSCHLAND GMBH	MOUNTING FOR A QUARTZ CRYSTAL	6463787	October 15, 2002
ATOTECH DEUTSCHLAND GMBH	Photosensitive composition	6451498	September 17, 2002

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	Process for plating metal coatings	6403168	June 11, 2002
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR THE ELECTROLYTIC PROCESSING ESPECIALLY OF FLAT ITEMS AND ARRANGEMENT FOR IMPLEMENTING THE PROCESS	6395163	May 28, 2002
ATOTECH DEUTSCHLAND GMBH	High current density zinc sulfate electrogalvanizing process and composition	6365031	April 2, 2002
ATOTECH DEUTSCHLAND GMBH	METHOD AND SOLUTION FOR PRODUCING GOLD COATING	6336962	January 8, 2002
ATOTECH DEUTSCHLAND GMBH	PALLADIUM COLLOID SOLUTION AND ITS UTILIZATION	6325910	December 4, 2001
ATOTECH DEUTSCHLAND GMBH	DEVICE AND METHOD FOR EVENING OUT THE THICKNESS OF METAL LAYERS ON ELECTRICAL CONTACT POINTS ON ITEMS THAT ARE TO BE TREATED	6319383	November 20, 2001
ATOTECH DEUTSCHLAND GMBH	Method of producing copper surfaces for improved bonding, compositions used therein and articles made therefrom	6284309	September 4, 2001
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR TREATING HOLES OR RECESSES EXTENDING INTO WORKPIECES WITH LIQUID TREATMENT MEDIA	6240934	June 5, 2001
ATOTECH DEUTSCHLAND GMBH	SOLUTION FOR PRETREATMENT OF ELECTRICALLY NON-CONDUCTIVE SURFACES, AND METHOD OF COATING THE SURFACES WITH SOLID MATERIAL PARTICLES	6235182	May 22, 2001

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	PROCESS FOR PLATING METAL COATINGS	6221440	April 24, 2001
ATOTECH DEUTSCHLAND GMBH	METHOD AND APPARATUS FOR ELECTROLYTICALLY TREATING A BOARD-SHAPED SUBSTRATE COMPRISING SHIELDING EDGE REGIONS OF THE SUBSTRATE DURING ELECTROLYTIC TREATMENT	6217736	April 17, 2001
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR THE PRECISE ELECTROLYTIC DEPOSITION AND ETCHING OF METAL LAYERS ON CIRCUIT BOARDS AND CONDUCTORS FOILS IN CONTINUOUS SYSTEMS	6186316	February 13, 2001
ATOTECH DEUTSCHLAND GMBH	CIRCUITRY AND METHOD FOR AN ELECTROPLATING PLANT OR ETCHING PLANT PULSE POWER SUPPLY	6179984	January 30, 2001
ATOTECH DEUTSCHLAND GMBH	METHOD AND APPARATUS FOR ELECTROLYTICALLY METALLISING OR ETCHING MATERIAL	6176995	January 23, 2001
ATOTECH DEUTSCHLAND GMBH	COMPUTERIZED METHOD AND SYSTEM FOR DESIGNING AN UHOLSTERED PART	6144890	November 7, 2000
ATOTECH DEUTSCHLAND GMBH	PROCESS AND CIRCUITRY FOR GENERATING CURRENT PULSES FOR ELECTROLYTIC METAL DEPOSITION	6132584	October 17, 2000
ATOTECH DUETSCHLAND GMBH	PROCESS FOR MANUFACTURING	6120672	September 19, 2000

Owner	Title	Patent No.	Issue Date
	INDUCTIVE COUNTING SYSTEMS		
ATOTECH DEUTSCHLAND GMBH	PROCEDURE AND DEVICE FOR THE CHEMICAL AND ELECTROLYTIC TREATMENT OF PRINTED CIRCUIT BOARDS AND CONDUCTOR FILMS	6077359	June 20, 2000
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR THE ELECTROCHEMICAL TREATMENT WITH TREATMENT LIQUID OF AN ITEM TO BE TREATED	6071400	June 6, 2000
ATOTECH DEUTSCHLAND GMBH	REMOVAL OF ORTHOPHOSPHITE IONS FROM ELECTROLESS NICKEL PLATING BATHS	6048585	April 11, 2000
Atotech USA, LLC (f/k/a Atotech USA, Inc.)	Fluid delivery method	6045874	April 4, 2000
ATOTECH DEUTSCHLAND GMBH	METHOD AND DEVICE FOR THE TREATMENT OF PLATE-SHAPED WORKPIECES HAVING SMALL HOLES	6016817	January 25, 2000
ATOTECH DEUTSCHLAND GMBH	Device for chemical and/or electrolytic (galvanic) metal deposition on a substrate (MULTIPLATE 2)	D822724	10-Jul-2018
ATOTECH DEUTSCHLAND GMBH	Method for increasing adhesion between a chromium surface and a lacquer	10,196,530	05-Feb-2019
ATOTECH DEUTSCHLAND GMBH	DESMEAR MODULE OF A HORIZONTAL PROCESS LINE AND A METHOD FOR SEPARATION AND REMOVAL OF DESMEAR PARTICLES FROM SUCH A DESMEAR MODULE	9930786	27-Mar-2018
ATOTECH DEUTSCHLAND GMBH	Method and apparatus for electrolytically depositing a deposition metal on a workpiece (Hochstromkontakt)	10774437	15-Sep-2020

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	ELECTROPLATING BATH AND METHOD FOR PRODUCING DARK CHROMIUM LAYERS	10006135	26-Jun-2018
ATOTECH DEUTSCHLAND GMBH	Method for fine line manufacturing	10,151,980	11-Dec-2018
ATOTECH DEUTSCHLAND GMBH	SUBSTRATE HOLDER FOR VERTICAL GALVANIC METAL DEPOSITION	10,407,793	10-Sep-2019
ATOTECH DEUTSCHLAND GMBH	Plating bath compositions for electroless plating of metals and metal alloys	9909216	06-Mar-2018
ATOTECH DEUTSCHLAND GMBH	SUBSTRATE HOLDER RECEPTION APPARATUS	10,260,161	16-Apr-2019
ATOTECH DEUTSCHLAND GMBH	Activation Method for Silicon Substrates	9,960,051	01-May-2018
ATOTECH DEUTSCHLAND GMBH	Electrolytic copper plating bath compositions and a method for their use	10,538,850	20-Apr-2016
ATOTECH DEUTSCHLAND GMBH	Surface treatment composition	10745568	18-Aug-2020
ATOTECH DEUTSCHLAND GMBH	Aqueous copper plating baths and a method for deposition of copper or copper alloy onto a substrate	10,767,275	08-Sep-2020
ATOTECH DEUTSCHLAND GMBH	Copper plating bath composition and method for deposition of copper	10,633,755	28-Apr-2020
ATOTECH DEUTSCHLAND GMBH	METHOD FOR GALVANIC METAL DEPOSITION	10,407,788	10-Sep-2019
ATOTECH DEUTSCHLAND GMBH	Process for indium or indium alloy deposition and article	10,753,007	25-Aug-2020
ATOTECH DEUTSCHLAND GMBH	Aqueous indium or indium alloy plating bath and process for deposition of indium or an indium alloy	10,793,962	06-Oct-2020
ATOTECH DEUTSCHLAND GMBH	Etching solution for copper and copper alloy surfaces	10,619,251	14-Apr-2020
ATOTECH DEUTSCHLAND GMBH	A non-aqueous stripping composition and a method of stripping an organic coating from a substrate	10,456,813	29-Oct-2019

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	Lead-Frame Structure, Lead-Frame, Surface Mount Electronic Device and Methods of Producing Same	10,832,997	10-Nov-2020
ATOTECH DEUTSCHLAND GMBH	Lead-Frame Structure, Lead-Frame, Surface Mount Electronic Device and Methods of Producing Same	10,867,895	15-Dec-2020
ATOTECH DEUTSCHLAND GMBH	Method for monitoring the total amount of brighteners in an acidic copper/copper alloy plating bath and controlled process for plating	10,494,732	03-Dec-2019
ATOTECH DEUTSCHLAND GMBH	Composition and process for metallizing nonconductive plastic surfaces	10,377,947	13-Aug-2019
ATOTECH DEUTSCHLAND GMBH	DEVICE FOR VERTICAL GALVANIC METAL DEPOSITION ON A SUBSTRATE	10,604,861	31-Mar-2020
ATOTECH DEUTSCHLAND GMBH	Wafer-like substrate processing method and apparatus	10,832,929	10-Nov-2020
ATOTECH DEUTSCHLAND GMBH	Pyridinium compounds, a synthesis method therefor, metal or metal alloy plating baths containing said pyridinium compounds and a method for use of said metal or metal alloy plating baths	10,882,842	05-Jan-2021
ATOTECH DEUTSCHLAND GMBH	MEMBRANE ELECTROLYSIS STACK, ELECTRODIALYSIS DEVICE INCLUDING THE STACK AND METHOD FOR THE REGENERATION OF AN ELECTROLESS PLATING BATH	9,669,361	06-Jun-2017
ATOTECH DEUTSCHLAND GMBH	COMPOSITION AND METHOD FOR REMOVAL OF ORGANIC PAINT COATINGS FROM SUBSTRATES	9,593,247	14-Mar-2017

Owner	Title	Patent No.	Issue Date
ATOTECH DEUTSCHLAND GMBH	METHOD FOR DEPOSITING A FIRST METALLIC LAYER ONTO NON-CONDUCTIVE POLYMERS	9,551,073	24-Jan-2017
ATOTECH DEUTSCHLAND GMBH	PLATING BATH COMPOSITION AND METHOD FOR ELECTROLESS PLATING OF PALLADIUM	10,513,780	24-Dec-2019
ATOTECH DEUTSCHLAND GMBH	METHOD FOR MANUFACTURING A PRINTED CIRCUIT BOARD	10,477,700	12-Nov-2019
ATOTECH DEUTSCHLAND GMBH	NOVEL METHOD FOR ELECTROMAGNETIC SHIELDING AND THERMAL MANAGEMENT OF ACTIVE COMPONENTS	10,249,572	02-Apr-2019

Patent Applications:

Owner	Title	Application No.	Application Date
ATOTECH DEUTSCHLAND GMBH	Imidazoyl Urea Polymers and their Use in Metal or Metal Alloy Plating Bath Compositions	15/748,203	19-Aug-2016
ATOTECH DEUTSCHLAND GMBH	Plating bath composition for electroless plating of gold and a method for depositing a gold layer	15/758754	16-Sep-2016
ATOTECH DEUTSCHLAND GMBH	Method for monitoring the total amount of sulphur containing compounds in a metal plating bath	15/774,299	02-Dec-2016
ATOTECH DEUTSCHLAND GMBH	Process for Depositing a Metal or Metal Alloy on a Surface of a Substrate Including its Activation	16/092,459	04-May-2017
ATOTECH DEUTSCHLAND GMBH	Method for directly depositing palladium onto a non-activated surface of a gallium nitride semiconductor	16/320,123	21-Aug-2017

Owner	Title	Application No.	Application Date
ATOTECH DEUTSCHLAND GMBH	MPS Nickel and Trichrome for improved corrosion resistance (Nissan Joint Patent)	16/291586	04-Mar-2019
ATOTECH DEUTSCHLAND GMBH	Transport Roller	16/345,747	21-Sep-2017
ATOTECH DEUTSCHLAND GMBH	Method of forming a solderable solder deposit on a contact pad	16/466,817	22-Dec-2017
ATOTECH DEUTSCHLAND GMBH	A method for electrolytically passivating an outermost chromium or outermost chromium alloy layer to increase corrosion resistance thereof	16/477,912	12-Feb-2018
ATOTECH DEUTSCHLAND GMBH	Automated substrate holder loading device	16/489,392	19-Feb-2018
ATOTECH DEUTSCHLAND GMBH	Controlled method for depositing a chromium or chromium alloy layer on at least one substrate	16/495,122	04-Apr-2018
ATOTECH DEUTSCHLAND GMBH	Method and apparatus for electroplating a metal onto a substrate	16/679,396	02-Dec-2015
ATOTECH DEUTSCHLAND GMBH	CLEANING SOLUTION COMPRISING A MIX OF POLYOXYALKYLENE NONIONIC SURFACTANTS FOR CLEANING METAL SURFACES	16/624,960	04-Jul-2018
ATOTECH DEUTSCHLAND GMBH	METHOD FOR ELECTROLYTICALLY DEPOSITING A ZINC-NICKEL ALLOY LAYER ON AT LEAST A SUBSTRATE TO BE TREATED	16/634,974	20-Aug-2018
ATOTECH DEUTSCHLAND GMBH	A bath and method for filling a vertical interconnect access or trench of a work piece with nickel or a nickel alloy	16/635,568	13-Sep-2018

Owner	Title	Application No.	Application Date
ATOTECH DEUTSCHLAND GMBH	A method for increasing corrosion resistance of a substrate comprising an outermost chromium alloy layer	16/772,339	11-Dec-2018
ATOTECH DEUTSCHLAND GMBH	Electroless gold plating bath	16/963,522	19-Nov-2018
ATOTECH DEUTSCHLAND GMBH	Metal or metal alloy deposition composition and plating compound	16/961,940	14-Dec-2018
ATOTECH DEUTSCHLAND GMBH	A method for increasing adhesion strength between a surface of copper or copper alloy and an organic layer	17/052,545	06-May-2019
ATOTECH DEUTSCHLAND GMBH	Aqueous indium or indium alloy plating bath and process for deposition of indium or an indium alloy	17/005,693	28-Aug-2020
ATOTECH DEUTSCHLAND GMBH	AN ACIDIC ZINC OR ZINC-NICKEL ALLOY ELECTROPLATING BATH FOR DEPOSITING A ZINC OR ZINC-NICKEL ALLOY LAYER	15/734,257	03-Jun-2019

Trademarks

Registered Trademarks:

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	ACIDCLEAN	24-Mar-2009	3593608
ATOTECH DEUTSCHLAND GMBH	ACTISALT	03-May-1966	0807896
ATOTECH DEUTSCHLAND GMBH	ALKALUME	08-Sep-1953	0579602
ATOTECH DEUTSCHLAND GMBH	ALPHA	02-Mar-1982	1191002
ATOTECH DEUTSCHLAND GMBH	ALSTAN	08-Sep-1987	1455971

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	ALUMETCH	06-Aug-2002	2603970
ATOTECH DEUTSCHLAND GMBH	ALUMSEAL	16-Jul-2002	2594032
ATOTECH DEUTSCHLAND GMBH	ANOKLEEN	03-Feb-1987	1427051
ATOTECH DEUTSCHLAND GMBH	APLUS	05-Jul-2014	4762571
ATOTECH DEUTSCHLAND GMBH	ARMOR	19-Feb-1991	1635201
ATOTECH DEUTSCHLAND GMBH	Bio Booster	17-Aug-2010	3833259
ATOTECH DEUTSCHLAND GMBH	BondFilm	04-Apr-2000	2339271
ATOTECH DEUTSCHLAND GMBH	BLUCR	25-Jul-2017	5248128
ATOTECH DEUTSCHLAND GMBH	CeraBond	12-Jun-2001	2459150
ATOTECH DEUTSCHLAND GMBH	COBALLOY	25-Dec-2001	2521499
ATOTECH DEUTSCHLAND GMBH	Condimat	18-Jun-2013	4599320
ATOTECH DEUTSCHLAND GMBH	CORRO TRIBLUE	24-Apr-2007	3232176
ATOTECH DEUTSCHLAND GMBH	CORROSIL	09-Jan-2007	3197089
ATOTECH DEUTSCHLAND GMBH	CorroTriBlue	12-May-2009	3617969
ATOTECH DEUTSCHLAND GMBH	CUFLEX	03-Nov-1964	779,284
ATOTECH DEUTSCHLAND GMBH	CU-LINK	03-Oct-1995	1924374
ATOTECH DEUTSCHLAND GMBH	CUPRABASE	21-Apr-2009	3609295
ATOTECH DEUTSCHLAND GMBH	CUPRACID	02-Feb-1971	907002
ATOTECH DEUTSCHLAND GMBH	CUPRAETCH	12-May-2009	3617971
ATOTECH DEUTSCHLAND GMBH	CUPRAPRO	25-Aug-2009	3673371

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	CUPRAPULSE	04-Jul-2000	2364524
ATOTECH DEUTSCHLAND GMBH	CupraTech	18-Aug-2015	4,796,106
ATOTECH DEUTSCHLAND GMBH	DUOZINC	25-May-1965	789867
ATOTECH DEUTSCHLAND GMBH	DURABOND	15-May-1990	1595920
ATOTECH DEUTSCHLAND GMBH	DYNACHROME	20-Apr-1999	2241064
ATOTECH DEUTSCHLAND GMBH	ECOLOZINC	03-Oct-1972	943893
ATOTECH DEUTSCHLAND GMBH	ECONO-CHROME	26-Feb-1963	745643
ATOTECH DEUTSCHLAND GMBH	ECOTRI	25-Apr-2006	3086502
ATOTECH DEUTSCHLAND GMBH	EDEN	29-Jul-2003	2742826
ATOTECH DEUTSCHLAND GMBH	ELECTROPURE	20-Oct-2020	6,177,464
ATOTECH DEUTSCHLAND GMBH	ELEVEN (fig.)	11-May-2010	3786523
ATOTECH DEUTSCHLAND GMBH	EVERPLATE	27-Mar-2001	2438138
ATOTECH DEUTSCHLAND GMBH	FERRODEX	03-Jun-1969	870598
ATOTECH DEUTSCHLAND GMBH	FUMETROL	03-Feb-1959	673349
ATOTECH DEUTSCHLAND GMBH	HIRON	14-Nov-2017	5331979
ATOTECH DEUTSCHLAND GMBH	HEEF	12-Oct-1987	1460498
ATOTECH DEUTSCHLAND GMBH	IniTech	18-Aug-2015	4,796,107
ATOTECH DEUTSCHLAND GMBH	INPULSE	16-Jul-2002	2595292
ATOTECH DEUTSCHLAND GMBH	INTERLOX	15-Mar-1960	694410
ATOTECH DEUTSCHLAND GMBH	KLEER AID	30-May-1972	0934772

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	LUMACHROME	08-Sep-1998	2187120
ATOTECH DEUTSCHLAND GMBH	Magnify	31-Mar-2009	3596957
ATOTECH DEUTSCHLAND GMBH	MARK	18-Feb-1964	0764886
ATOTECH DEUTSCHLAND GMBH	MASTER REMOVER	12-Nov-2013	4431393
ATOTECH DEUTSCHLAND GMBH	MULTIBOND	19-Dec-1995	1943216
ATOTECH DEUTSCHLAND GMBH	NEOGANTH	27-May-1986	1394540
ATOTECH DEUTSCHLAND GMBH	NeoLink	26-Mar-2013	4,309,433
ATOTECH DEUTSCHLAND GMBH	NiccoTech	18-Aug-2015	4,796,108
ATOTECH DEUTSCHLAND GMBH	NICHEM	13-Nov-2001	2506509
ATOTECH DEUTSCHLAND GMBH	NIFLOR	11-Feb-1986	1382726
ATOTECH DEUTSCHLAND GMBH	NIFLOR	25-Jun-1985	1343698
ATOTECH DEUTSCHLAND GMBH	NIKOTECT	12-Nov-2002	2650225
ATOTECH DEUTSCHLAND GMBH	NORTEX	13-Apr-1982	1193475
ATOTECH DEUTSCHLAND GMBH	NOVIGANTH	31-Jan-1967	823240
ATOTECH DEUTSCHLAND GMBH	PallaBond	16-Oct-2012	4224620
ATOTECH DEUTSCHLAND GMBH	PD-TECH	13-Jan-1998	2128462
ATOTECH DEUTSCHLAND GMBH	PRINTOGANTH	27-May-1986	1394539
ATOTECH DEUTSCHLAND GMBH	PROTECTOSTAN	05-Jul-2011	3990390
ATOTECH DEUTSCHLAND GMBH	PROTOLUX	01-Nov-1977	1076198
ATOTECH DEUTSCHLAND GMBH	QUATRASID	17-Mar-1964	766559

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	RECOTECT	12-Jun-2012	4156131
ATOTECH DEUTSCHLAND GMBH	REFLECTA	31-Oct-1972	946153
ATOTECH DEUTSCHLAND GMBH	REFLECTALLOY	23-Jul-1996	1988409
ATOTECH DEUTSCHLAND GMBH	RESISTSTRIP	24-Mar-2009	3593609
ATOTECH DEUTSCHLAND GMBH	RODIP	25-Jun-1957	647290
ATOTECH DEUTSCHLAND GMBH	ROGARD	23-Mar-1965	786989
ATOTECH DEUTSCHLAND GMBH	ROKLEEN	22-Oct-1963	758971
ATOTECH DEUTSCHLAND GMBH	ROPLATE	12-Sep-1967	834938
ATOTECH DEUTSCHLAND GMBH	SATILUME	05-Dec-2000	2410592
ATOTECH DEUTSCHLAND GMBH	SECURIGANTH	27-May-1986	1394538
ATOTECH DEUTSCHLAND GMBH	Semilux	28-Nov-2014	1239720
ATOTECH DEUTSCHLAND GMBH	SIGMATECH	29-Aug-2011	4188643
ATOTECH DEUTSCHLAND GMBH	SILVER-LUME	09-Sep-1958	666740
ATOTECH DEUTSCHLAND GMBH	SOLDERBOND	03-Apr-2001	2441559
ATOTECH DEUTSCHLAND GMBH	Spherolyte	10-Jan-2012	4082886
ATOTECH DEUTSCHLAND GMBH	SRHS	18-Oct-1955	614153
ATOTECH DEUTSCHLAND GMBH	StannoPure	11-Nov-2008	3529591
ATOTECH DEUTSCHLAND GMBH	SUPREME	01-Oct-1985	1363874
ATOTECH DEUTSCHLAND GMBH	TECHDIP	04-Apr-2017	5174285
ATOTECH DEUTSCHLAND GMBH	TECHSEAL	28-May-2002	2572820

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	TeloTech	19-Apr-2016	4,941,850
ATOTECH DEUTSCHLAND GMBH	TINPEST GARD	29-Jan-1980	1129752
ATOTECH DEUTSCHLAND GMBH	TRICHROME	15-Jul-2008	3468468
ATOTECH DEUTSCHLAND GMBH	TRI-CHROME	04-Apr-1978	1088444
ATOTECH DEUTSCHLAND GMBH	TRIDUR	15-Feb-2011	3918383
ATOTECH DEUTSCHLAND GMBH	TRI-MAX	04-Sep-1990	1611809
ATOTECH DEUTSCHLAND GMBH	TRI-MAX (fig.)	23-Jul-1991	1651249
ATOTECH DEUTSCHLAND GMBH	TRU-PLATE	26-Apr-1977	1064214
ATOTECH DEUTSCHLAND GMBH	UNIBRITE (former UNI-BRITE)	14-Jun-1994	1839149
ATOTECH DEUTSCHLAND GMBH	UNICHROME	17-Sep-1935	328162
ATOTECH DEUTSCHLAND GMBH	UNICHROME	16-Jul-1946	422307
ATOTECH DEUTSCHLAND GMBH	UniClean	15-Sep-1998	2188776
ATOTECH DEUTSCHLAND GMBH	UNICOAT	12-Jun-2018	5492902
ATOTECH DEUTSCHLAND GMBH	UNIFIX	19-May-2009	3624341
ATOTECH DEUTSCHLAND GMBH	UNIPLATE	28-Mar-2000	2334982
ATOTECH DEUTSCHLAND GMBH	UniPrep	06-Dec-2005	3024158
ATOTECH DEUTSCHLAND GMBH	UniPrep	13-Dec-2005	3025193
ATOTECH DEUTSCHLAND GMBH	UniSpray	14-Mar-2006	3037242
ATOTECH DEUTSCHLAND GMBH	UniStrip	11-Apr-2006	3078258
ATOTECH DEUTSCHLAND GMBH	ZINTEK	25-Mar-2003	2699176

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	ZODIAC	27-Aug-1974	991786
ATOTECH DEUTSCHLAND GMBH	ZYLITE	21-Sep-2004	2886179
ATOTECH DEUTSCHLAND GMBH	CELEROLYTE	17-Jan-17	5121644
ATOTECH DEUTSCHLAND GMBH	INNOLYTE	25-Oct-16	5066602
ATOTECH DEUTSCHLAND GMBH	SEMILUX	24-Nov-15	4857311
ATOTECH DEUTSCHLAND GMBH	VISIOPLATE	13-Oct-15	4829364
ATOTECH DEUTSCHLAND GMBH	ECOPASS	25-Aug-15	4797503
ATOTECH DEUTSCHLAND GMBH	APLUS	30-Jun-15	4762571
ATOTECH DEUTSCHLAND GMBH	ATOMPLATE	5-May-15	4729754
ATOTECH DEUTSCHLAND GMBH	ECOPACT	4-Nov-14	4630463
ATOTECH DEUTSCHLAND GMBH	CONDIMAT	9-Sep-14	4599320
ATOTECH DEUTSCHLAND GMBH	ZINNI	9-Jul-13	4362921
ATOTECH DEUTSCHLAND GMBH	SIGMATECH	14-Aug-12	4188643
ATOTECH DEUTSCHLAND GMBH	ECOGANTH	27-Dec-11	4075882
ATOTECH DEUTSCHLAND GMBH	ATOTECH	4-Nov-08	3527689
ATOTECH DEUTSCHLAND GMBH	A	20-May-08	3431500
ATOTECH DEUTSCHLAND GMBH	XENOLYTE	15-Apr-08	3411852
ATOTECH DEUTSCHLAND GMBH	TRICOTECT	30-Oct-07	3324835
ATOTECH DEUTSCHLAND GMBH	KLEERAID	3-Jul-07	3259000
ATOTECH DEUTSCHLAND GMBH	ADHEMAX	29-May-07	3247855

Owner	Mark	Registration Date	Registration No.
ATOTECH DEUTSCHLAND GMBH	TRISEAL	24-Oct-06	3162929
ATOTECH DEUTSCHLAND GMBH	ATOMPURE	Jun. 02, 2016	1306551

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